

NC217 GEL FLUX

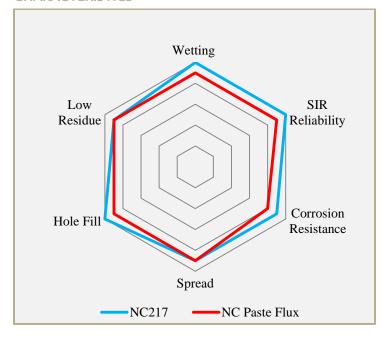
FEATURES

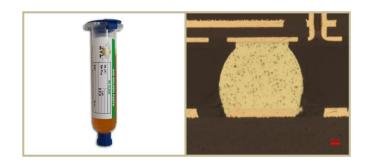
- Formulated for Rework and Repair
- Ideal for BGA Wide Process Window/Low Voiding
- Tin-Lead and Lead-Free Compatible
- Electrically Safe Unheated

DESCRIPTION

NC217 Gel Flux is specifically designed for touch-up and repair work. NC217 has a gel-like consistency minimizing spreading during rework and improving heat transfer from the soldering iron tip or hot air source. NC217 provides a much wider process window than liquid flux and lower residue than tacky flux. Gel flux spreading beyond the heated rework area, once dry, passes J-STD-004A and B unheated. NC217 dries within one hour of use with or without heat and is tack-free after four hours.

CHARACTERISTICS





HANDLING & STORAGE

| Parameter | Time | Temperature |
|-----------------------------------|--------|----------------------|
| Sealed Refrigerated Shelf Life | 1 Year | 4°C-12°C (40°F-55°F) |
| Sealed Unrefrigerated | 6 | Room Temperature |
| Shelf Life | Months | |

NC217 has a sealed shelf life of one (1) year when stored 4°C-12°C (40°F-55°F). Do not store near fire or flame. Keep away from sunlight as it may degrade product. NC217 is shipped ready-to-use, no mixing necessary. Do not mix used and unused chemicals in the same container. Reseal any opened containers. After opening, gel flux shelf life is environment and application dependent.

APPLICATION

NC217 is formulated for application via dispense needle, brush, or a cotton swab. NC217 is ready to use directly from its container, no thinning required

PROCESS GUIDELINES

NC217 should be applied sparingly to solderable surfaces prior to heat application. NC217 can be used with soldering irons, hot air pencils, BGA rework stations or micro ovens. Reflow profile will be alloy and thermal mass dependent. For processing assistance, please contact AIM Technical Support by visiting http://www.aimsolder.com/technical-support-contacts.

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TECHNICAL DATA SHEET



CLEANING

NC217 Gel Flux residues do not require removal. However, residues can be easily cleaned if necessary using common flux removers. Isopropyl alcohol (IPA) is not recommended. Contact AIM for additional cleaning information.

SAFETY

Use with adequate ventilation and proper personal protective equipment. Refer to the accompanying Safety Data Sheet for any specific emergency information. Do not dispose of any hazardous materials in non-approved containers.

TEST DATA SUMMARY

| Name | Test Method | Results | |
|---|---|-------------|-----------------|
| IPC Flux Classification | J-STD-004 | ROL0 | |
| Name | Test Method | Results | lmage |
| Copper Mirror | J-STD-004B 3.4.1.1 IPC-TM-650 2.3.32 | LOW | NC 217 33725 |
| Corrosion | J-STD-004B 3.4.1.2 IPC-TM-650 2.6.15 | PASS | Before After |
| Quantitative Halides | J-STD-004B 3.4.1.3 IPC-TM-650 2.3.28.1 | ≤ 0 .0 | |
| Qualitative Halides, Silver Chromate | J-STD-004B 3.5.1.1 IPC-TM-650 2.3.33 | PASS | |
| Qualitative Halides, Fluoride Spot | J-STD-004B 3.5.1.2 IPC-TM-650 2.3.35.1 | No Fluoride | |

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TECHNICAL DATA SHEET



| Name | Test Method | Results | Image |
|----------------------------------|--|--|--|
| Surface Insulation Resistance | J-STD-004B 3.4.1.4 IPC-TM-650 2.6.3.7 | PASS | 11 10 (e.g.) (e. |
| | J-STD-004 3.4.1.4 IPC-TM-650 2.6.3.3 | PASS | 6 5 6 7 1 |
| Acid Value Determination | J-STD-004B 3.4.2.2 IPC-TM-650 2.3.13 | 167 mg KOH per gram flux Typical | |
| Viscosity | J-STD-004B 3.4.2.4 IPC-TM-650 2.4.34 | 100 – 160 kcps | |
| Visual | J-STD-004B 3.4.2.5 | Yellow - Orange | |
| Wetting | J-STD-005A 3.9 IPC-TM-650 2.4.45 | PASS | |

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